# LNJ612W8WRA

Surface Mounting Chip LED

TSS Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	40	mW	
Forward current	I <sub>F</sub>	10	mA	
Pulse forward current *	I <sub>FP</sub>	40	mA	
Reverse voltage	V <sub>R</sub>	5	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Lighting Color

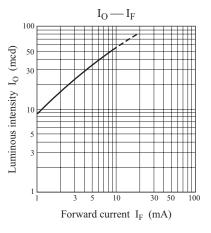
• Pure Green

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

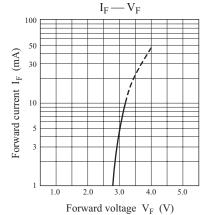
#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

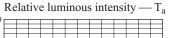
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Luminous intensity *	I <sub>O</sub>	$I_F = 5 \text{ mA}$	10.3	34.0		mcd	
Reverse current	I <sub>R</sub>	$V_R = 5 V$			10	μΑ	
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$		3.0	3.7	V	
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 5  {\rm mA}$		525		nm	
Spectral half band width	Δλ	$I_{\rm F} = 5  {\rm mA}$		45		nm	

Note) \*: Measurement tolerance: ±20%

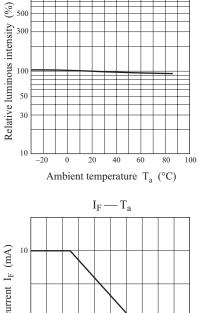


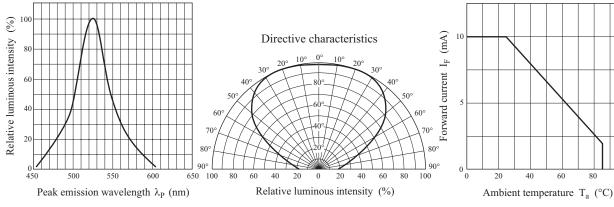
Relative luminous intensity —  $\lambda_P$ 





1 0 0 0



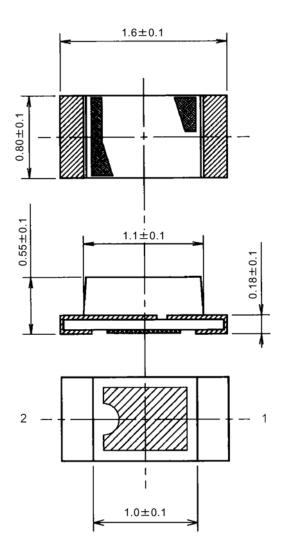


Publication date: December 2008

100

Package (Unit: mm)

### KLTFTN2K1200



• Pin name

1: Anode

2: Cathode

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